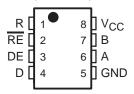
- Designed for Signaling Rates<sup>†</sup> Up to 30 Mbps
- Bus-Pin ESD Protection Exceeds 12 kV HBM
- Compatible With ANSI Standard TIA/EIA-485-A and ISO 8482:1987(E)
- Low Skew
- Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments
- Very Low Disabled Supply-Current Requirements . . . 700 μA Maximum
- Common Mode Voltage Range of –7 V to 12 V
- Thermal-Shutdown Protection
- Driver Positive and Negative Current Limiting
- Open-Circuit Failsafe Receiver Design
- Receiver Input Sensitivity . . . ±200 mV Max
- Receiver Input Hysteresis . . . 50 mV Typ
- Glitch-Free Power-Up and Power-Down Protection
- Available in Q-Temp Automotive
   High Reliability Automotive Applications
   Configuration Control / Print Support
   Qualification to Automotive Standards

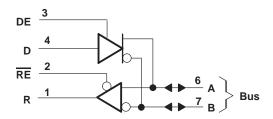
### description

The SN65LBC176A, SN65LBC176AQ, and SN75LBC176A differential bus transceivers are monolithic, integrated circuits designed for bidirectional data communication on multipoint bus-transmission lines. They are designed for balanced transmission lines and are compatible with ANSI standard TIA/EIA-485-A and ISO 8482. The A version offers improved switching performance over its predecessors without sacrificing significantly more power.

SN65LBC176AQD (Marked as B176AQ) SN65LBC176AD (Marked as BL176A) SN65LBC176AP (Marked as 65LBC176A) SN75LBC176AD (Marked as LB176A) SN75LBC176AP (Marked as 75LBC176A) (TOP VIEW)



### logic diagram (positive logic)



### **Function Tables**

### DRIVER

INPUT	ENABLE	OUTPUTS
D	DE	A B
Н	Н	H L
L	Н	L H
X	L	Z Z
Open	Н	H L

### RECEIVER

DIFFERENTIAL INPUTS VA-VB	ENABLE RE	OUTPUT R
V <sub>ID</sub> ≥ 0.2 V	L	Н
-0.2 V < V <sub>ID</sub> < 0.2 V	L	?
V <sub>ID</sub> ≤ −0.2 V	L	L
X	Н	Z
Open	L	Н

H = high level, L = low level, ? = indeterminate,

X = irrelevant, Z = high impedance (off)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

† Signaling rate by TIA/EIA-485-A definition restrict transition times to 30% of the bit duration, and much higher signaling rates may be achieved using a different criteria (see *TYPICAL CHARACTERISTICS* section).



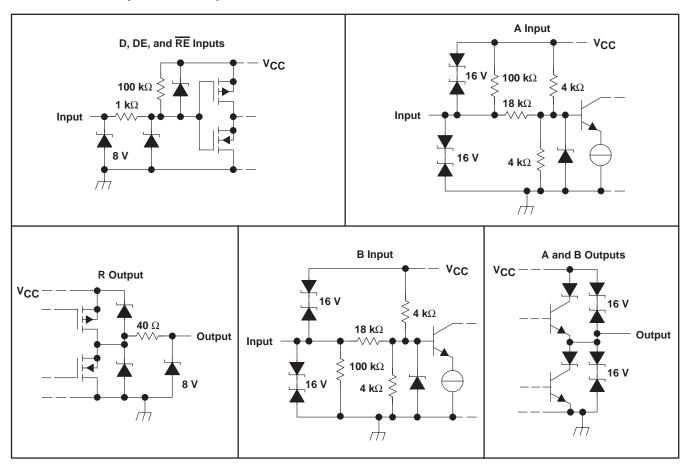
### description (continued)

The SN65LBC176A, SN65LBC176AQ, and SN75LBC176A combine a 3-state, differential line driver and a differential input line receiver, both of which operate from a single 5-V power supply. The driver and receiver have active-high and active-low enables, respectively, which can externally connect together to function as a direction control. The driver differential outputs and the receiver differential inputs connect internally to form a differential input/output (I/O) bus port that is designed to offer minimum loading to the bus whenever the driver is disabled or  $V_{CC} = 0$ . This port features wide positive and negative common-mode voltage ranges, making the device suitable for party-line applications. Very low device supply current can be achieved by disabling the driver and the receiver.

### **AVAILABLE OPTIONS**

	P#	ACKAGE
TA	SMALL OUTLINE (D)	PLASTIC DUAL-IN-LINE
0°C to 70°C	SN75LBC176AD	SN75LBC176AP
-40°C to 85°C	SN65LBC176AD	SN65LBC176AP
-40°C to 125°C	SN65LBC176AQD	_

### schematics of inputs and outputs



### absolute maximum ratings†

Supply voltage, Voc (see Not	e 1)	
	ninal (A or B)	
	· <del>RE</del> )`	
Electrostatic discharge: Bus te	erminals and GND, Class 3, A: (see Note 2)	12 kV
Bus te	erminals and GND, Class 3, B: (see Note 2)	400 V
All ter	minals, Class 3, A:	3 kV
All ter	minals, Class 3, B:	400 V
Continuous total power dissip	ation (see Note 3)	See Dissipation Rating Table
Storage temperature range, T	- stg ·····	65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential I/O bus voltage, are with respect to network ground terminal.
  - 2. Tested in accordance with MIL-STD-883C, Method 3015.7
  - 3. The maximum operating junction temperature is internally limited. Use the dissipation rating table to operate below this temperature.

### **DISSIPATION RATING TABLE**

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	A · · · A · · · · · · · · · · · · · · ·		T <sub>A</sub> = 85°C POWER RATING	T <sub>A</sub> = 125°C POWER RATING
D	725 mW	5.8 mW/°C	464 mW	377 mW	145 mW
Р	1000 mW	8.0 mW/°C	640 mW	520 mW	_

<sup>‡</sup> This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

### recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>				5.25	V
Voltage at any bus terminal (separately or common	mode), V <sub>I</sub> or V <sub>IC</sub>	-7		12	V
High-level input voltage, VIH	D, DE, and RE	2		VCC	V
Low-level input voltage, V <sub>IL</sub>	D, DE, and RE	0		0.8	V
Differential input voltage, V <sub>ID</sub> (see Note 4)				12	V
	Driver	-60			4
High-level output current, IOH	Receiver	-8			mA
	Driver			60	
Low-level output current, IOL	Receiver			8	mA
	SN65LBC176AQ	-40		125	
Operating free-air temperature, T <sub>A</sub>	SN65LBC176A	-40		85	°C
	SN75LBC176A	0		70	

<sup>§</sup> The algebraic convention, in which the least positive (most negative) limit is designated as minimum, is used in this data sheet. NOTE 4. Differential input/output bus voltage is measured at the noninverting terminal A with respect to the inverting terminal B.



### SN65LBC176A, SN75LBC176A DIFFERENTIAL BUS TRANSCEIVERS

SLLS376D- MAY 2000 - REVISED JULY 2008

### driver electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER		TEST CONDITIONS	6	MIN	TYP <sup>†</sup>	MAX	UNIT
VIK	Input clamp voltage	$I_I = -18 \text{ mA}$				-0.8		V
				SN65LBC176AQ	1.5	4	6	
		IO = 0		SN65LBC176A, SN75LBC176A		4		V
				SN65LBC176AQ	0.9	1.5	6	
VOD	Differential output voltage	$R_L = 54 \Omega$ ,	See Figure 1	SN65LBC176A	1	1.5	3	V
. 02 .				SN75LBC176A	1.1	1.5	3	V
				SN65LBC176AQ	0.9	1.5	6	V
		$V_{test} = -7 V to$	12 V, See Figure 2	SN65LBC176A	1	1.5	3	V
				SN75LBC176A	1.1	1.5	3	V
Δ  V <sub>OD</sub>	Change in magnitude of differential output voltage	See Figures 1 and 2					0.2	V
		SN65LBC176A0 SN65LBC176A0 SN65LBC176A0 SN75LBC176A0 SN65LBC176A0 SN65LBC176A0 SN75LBC176A0 SN75LBC176A0			1.8	2.4	3	
VOC(SS)	Steady-state common-mode output voltage				1.8	2.4	2.8	.,,
					-0.2		0.2	V
$_{\Delta}$ VOC(SS)	Change in steady-state common-mode output voltage				-0.1		0.1	
loz	High-impedance output current	See receiver in	put currents					
lіН	High-level enable input current	V <sub>I</sub> = 2 V	V <sub>I</sub> = 2 V					μА
I <sub>I</sub> L	Low-level enable input current	V <sub>I</sub> = 0.8 V						μΑ
los	Short-circuit output current	$-7 \text{ V} \le \text{V}_{\text{O}} \le 12 \text{ V}$					250	mA
			Receiver disabled an	oled and driver enabled		5	9	
lcc	Supply current	V <sub>I</sub> = 0 or V <sub>CC</sub> , Receiver disabled and		d driver disabled		0.4	0.7	mA
			Receiver enabled and	d driver enabled		8.5	15	

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC}$  = 5 V,  $T_A$  = 25°C.

# driver switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST	SN65LBC176AQ			SN6 SN7	UNIT		
		CONDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	
tPLH	Propagation delay time, low-to-high-level output		2		12	2	6	12	ns
tPHL	Propagation delay time, high-to-low-level output	$R_1 = 54 \Omega$ ,	2		12	2	6	12	ns
tsk(p)	Pulse skew (  t <sub>PLH</sub> - t <sub>PHL</sub>  )	$C_{L} = 50 \text{ pF},$			2		0.3	1	ns
t <sub>r</sub>	Differential output signal rise time	See Figure 3	1.2		11	4	7.5	11	ns
tf	Differential output signal fall time	]	1.2		11	4	7.5	11	ns
<sup>t</sup> PZH	Propagation delay time, high-impedance-to-high-level output	$R_L = 110 \Omega$ , See Figure 4			22		12	22	ns
tPZL	Propagation delay time, high-impedance-to-low-level output	$R_L = 110 \Omega$ , See Figure 5			25		12	22	ns
<sup>t</sup> PHZ	Propagation delay time, high-level-to-high- impedance output	$R_L = 110 \Omega$ , See Figure 4			22		12	22	ns
t <sub>PLZ</sub>	Propagation delay time, low-level-to-high-impedance output	R <sub>L</sub> = 110 $\Omega$ , See Figure 5	·	·	22		12	22	ns

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



## receiver electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER		TEST CONDITION	MIN	TYP <sup>†</sup>	MAX	UNIT	
V <sub>IT+</sub>	Positive-going input threshold voltage	I <sub>O</sub> = -8 mA					0.2	V
VIT-	Negative-going input threshold voltage	IO = 8 mA			-0.2			V
V <sub>hys</sub>	Hysteresis voltage (V <sub>IT+</sub> – V <sub>IT-</sub> )	1 ~				50		mV
VIK	Enable-input clamp voltage	$I_{I} = -18 \text{ mA}$			-1.5	-0.8		V
Vон	High-level output voltage	$V_{ID} = 200 \text{ mV},$	$I_{OH} = -8 \text{ mA},$	See Figure 6	4	4.9		V
VOL	Low-level output voltage	$V_{ID} = -200 \text{ mV},$	$I_{OL} = 8 \text{ mA},$	See Figure 6		0.1	8.0	V
	18.1.1			SN65LBC176AQ	-10		10	
loz	High-impedance-state output current			SN65LBC176A, SN75LBC176A	-1		1	μΑ
		V <sub>IH</sub> = 12 V, V <sub>CC</sub> = 5 V				0.4	1	
l.	Bus is and summed	V <sub>IH</sub> = 12 V,	VCC = 0	Other leader at 0.1/		0.5	1	4
11	Bus input current	$V_{IH} = -7 V$	V <sub>CC</sub> = 5 V	Other input at 0 V	-0.8	-0.4		mA
		$V_{IH} = -7 V$	VCC = 0	7	-0.8	-0.3		
lіН	High-level enable-input current	V <sub>IH</sub> = 2 V			-100			μΑ
IIL	Low-level enable-input current	V <sub>IL</sub> = 0.8 V			-100			μΑ
		.,,	Receiver enabled and driver disabled			4	7	
ICC	Supply current	$V_I = 0$ or $V_{CC}$ , Receiver disabled and driver disabled			0.4	0.7	mA	
		110 1000	Receiver enabled	Receiver enabled and driver enabled		8.5	15	

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

# receiver switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	SN6	5LBC170	6AQ	SN6 SN7	UNIT		
			MIN	TYP <sup>†</sup>	MAX	MIN	TYP <sup>†</sup>	MAX	
t <sub>PLH</sub>	Propagation delay time, output↑		7		30	7	13	20	ns
tPHL	Propagation delay time, output↓	V <sub>ID</sub> = -1.5 V to 1.5 V, See Figure 7	7		30	7	13	20	ns
tsk(p)	Pulse skew ( tpHL -tpLH )	Occ riguic 7			6		0.5	1.5	ns
t <sub>r</sub>	Rise time, output	See Figure 7			5		2.1	3.3	ns
t <sub>f</sub>	Fall time, output	See Figure 7			5		2.1	3.3	ns
<sup>t</sup> PZH	Output enable time to high level				50		30	45	ns
		C <sub>L</sub> = 10 pF,			50		30	45	ns
		See Figure 8			60		20	40	ns
tPLZ	Output disable time from low level				40		20	40	ns

<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.



### PARAMETER MEASUREMENT INFORMATION

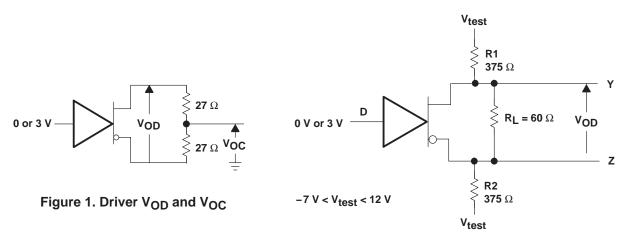
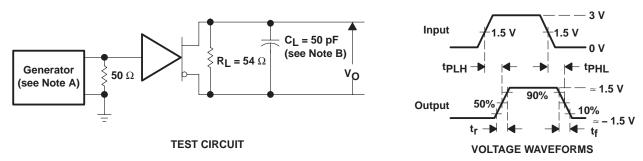
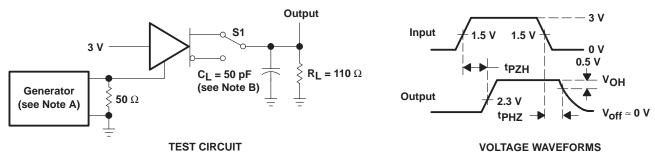


Figure 2. Driver V<sub>OD3</sub>



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle,  $t_f \leq$  6 ns,  $t_f \leq$  8 ns,  $t_f \leq$  8 ns,  $t_f \leq$  9 ns,  $t_f$ 
  - B. C<sub>L</sub> includes probe and jig capacitance.

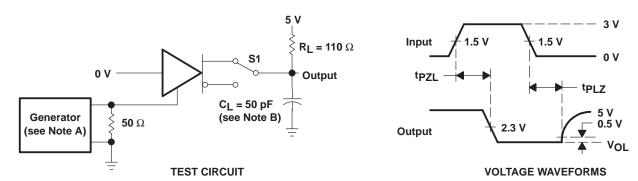
Figure 3. Driver Test Circuit and Voltage Waveforms



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle,  $t_{\Gamma} \leq$  6 ns,  $t_{\Gamma} \leq$  7 ns,  $t_{\Gamma} \leq$  8 ns,  $t_{\Gamma} \leq$  9 ns,  $t_$ 
  - B. CL includes probe and jig capacitance.

Figure 4. Driver Test Circuit and Voltage Waveforms

### PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle,  $t_{f} \leq$  6 ns,  $t_{f} \leq$  6 ns,  $t_{Q} = 50 \Omega$ .
  - B. C<sub>L</sub> includes probe and jig capacitance.

Figure 5. Driver Test Circuit and Voltage Waveforms

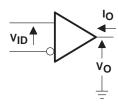
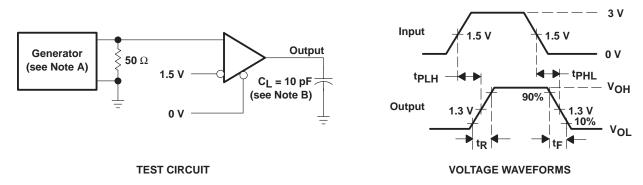


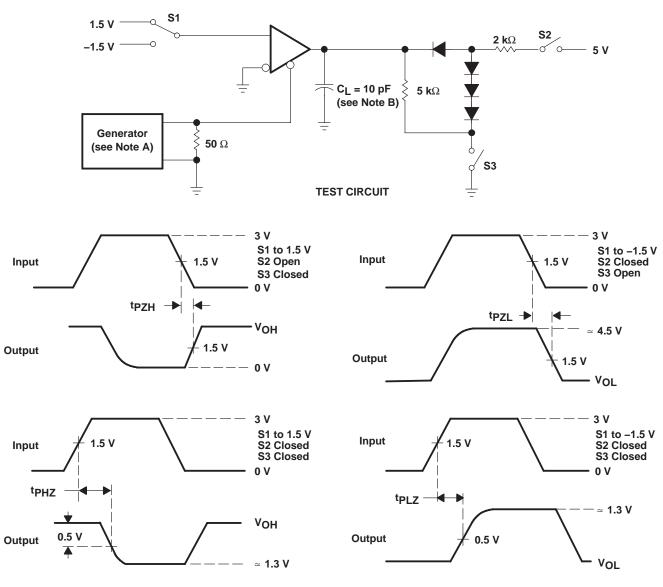
Figure 6. Receiver VOH and VOL



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle,  $t_{\Gamma} \leq$  6 ns,  $t_{\Gamma} \leq$  7 ns,  $t_{\Gamma} \leq$  8 ns,  $t_{\Gamma} \leq$  8 ns,  $t_{\Gamma} \leq$  9 ns,  $t_$ 
  - B. C<sub>I</sub> includes probe and jig capacitance.

Figure 7. Receiver Test Circuit and Voltage Waveforms

### PARAMETER MEASUREMENT INFORMATION



**VOLTAGE WAVEFORMS** 

NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle,  $t_{\Gamma} \leq$  6 ns,  $t_{\Gamma} \leq$  7 ns,  $t_{\Gamma} \leq$  8 ns,  $t_{\Gamma} \leq$  8 ns,  $t_{\Gamma} \leq$  9 ns,  $t_$ 

B. C<sub>L</sub> includes probe and jig capacitance.

Figure 8. Receiver Test Circuit and Voltage Waveforms

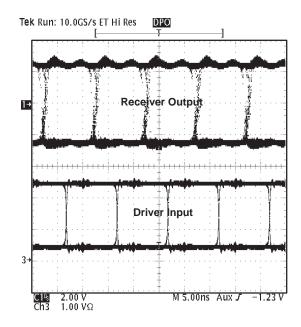




Figure 9. Typical Waveform of Non-Return-To-Zero (NRZ), Pseudorandom Binary Sequence (PRBS) Data at 100 Mbps Through 15m, of CAT 5 Unshielded Twisted Pair (UTP) Cable

TIA/EIA-485-A defines a maximum signaling rate as that in which the transition time of the voltage transition of a logic-state change remains less than or equal to 30% of the bit length. Transition times of greater length perform quite well even though they do not meet the standard definition.

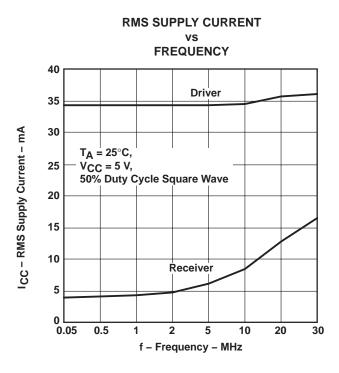


Figure 10

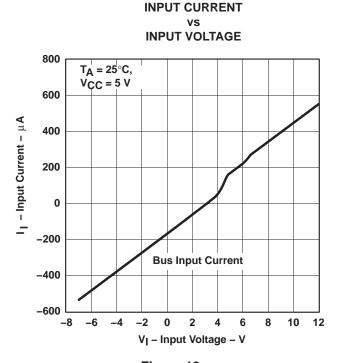


Figure 12

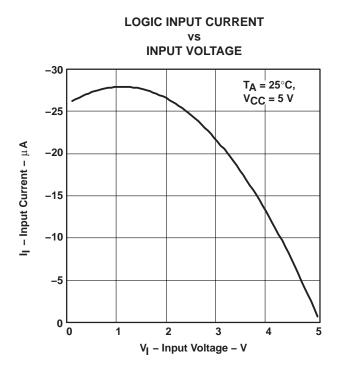


Figure 11

# LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT

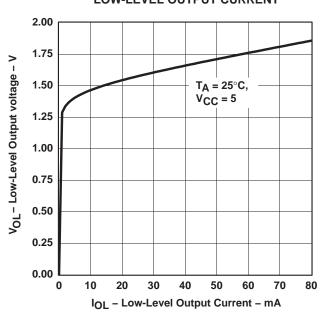


Figure 13

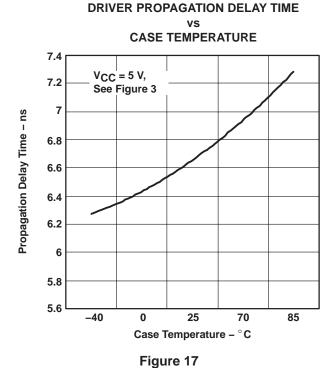
### **DRIVER HIGH-LEVEL OUTPUT VOLTAGE HIGH-LEVEL OUTPUT CURRENT** 5 4.5 VOH - High-Level Output Voltage - V V<sub>CC</sub> = 5.25 V 3.5 3 2.5 $V_{CC} = 5 V$ 2 $V_{CC} = 4.75 V$ 1.5 TA = 25°C 1 0.5 -50 -30 -40 -60 I<sub>OH</sub> - High-Level Output Current - (mA)

Figure 14

# DRIVER DIFFERENTIAL OUTPUT VOLTAGE VS CASE TEMPERATURE 1.5 $V_{CC} = 5 \text{ V}, R_L = 54 \Omega, V_{IH} = 3 \text{ V}$ $V_{CC} = 5 \text{ V}, R_L = 54 \Omega, V_{IH} = 3 \text{ V}$

Figure 15

### RECEIVER PROPAGATION TIME **CASE TEMPERATURE** 13.8 $V_{CC} = 5 V$ , 13.7 See Figure 7 13.6 TPHL Receiver (ns) 13.5 13.4 13.3 13.2 13.1 13 12.9 -40 25 80 Case Temperature °C Figure 16



# DRIVER OUTPUT CURRENT vs SUPPLY VOLTAGE

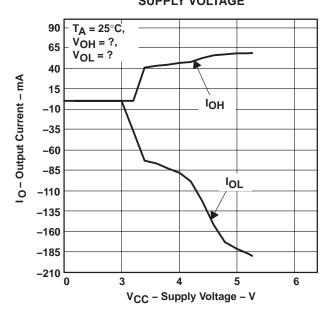


Figure 18





6-Feb-2020

### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN65LBC176AD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	BL176A	Samples
SN65LBC176ADR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	BL176A	Samples
SN65LBC176ADRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	BL176A	Samples
SN65LBC176AP	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	-40 to 85	65LBC176A	Samples
SN65LBC176AQD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 125	B176AQ	Samples
SN65LBC176AQDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM		B176AQ	Samples
SN65LBC176AQDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 125	B176AQ	Samples
SN65LBC176AQDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM		B176AQ	Samples
SN75LBC176AD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	LB176A	Samples
SN75LBC176ADG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	LB176A	Samples
SN75LBC176ADR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	LB176A	Samples
SN75LBC176ADRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	LB176A	Samples
SN75LBC176AP	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	0 to 70	75LBC176A	Samples

<sup>(1)</sup> The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.



### PACKAGE OPTION ADDENDUM

6-Feb-2020

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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### OTHER QUALIFIED VERSIONS OF SN65LBC176A:

Enhanced Product: SN65LBC176A-EP

NOTE: Qualified Version Definitions:

Enhanced Product - Supports Defense, Aerospace and Medical Applications

### PACKAGE MATERIALS INFORMATION

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### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65LBC176ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN65LBC176AQDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75LBC176ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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### \*All dimensions are nominal

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	Device	Package Type	Package Drawing	Pins SPQ		Length (mm)	Width (mm)	Height (mm)	
	SN65LBC176ADR	SOIC	D	8	2500	340.5	338.1	20.6	
	SN65LBC176AQDR	SOIC	D	8	2500	340.5	338.1	20.6	
	SN75LBC176ADR	SOIC	D	8	2500	340.5	338.1	20.6	



SMALL OUTLINE INTEGRATED CIRCUIT



### NOTES:

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



### NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



### P (R-PDIP-T8)

### PLASTIC DUAL-IN-LINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



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